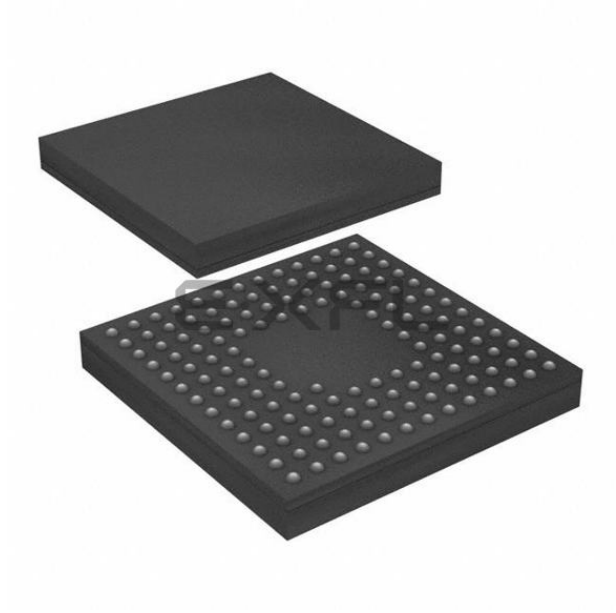
Renesas Electronics America Inc - R5F5210ABDLK#U0 Datasheet



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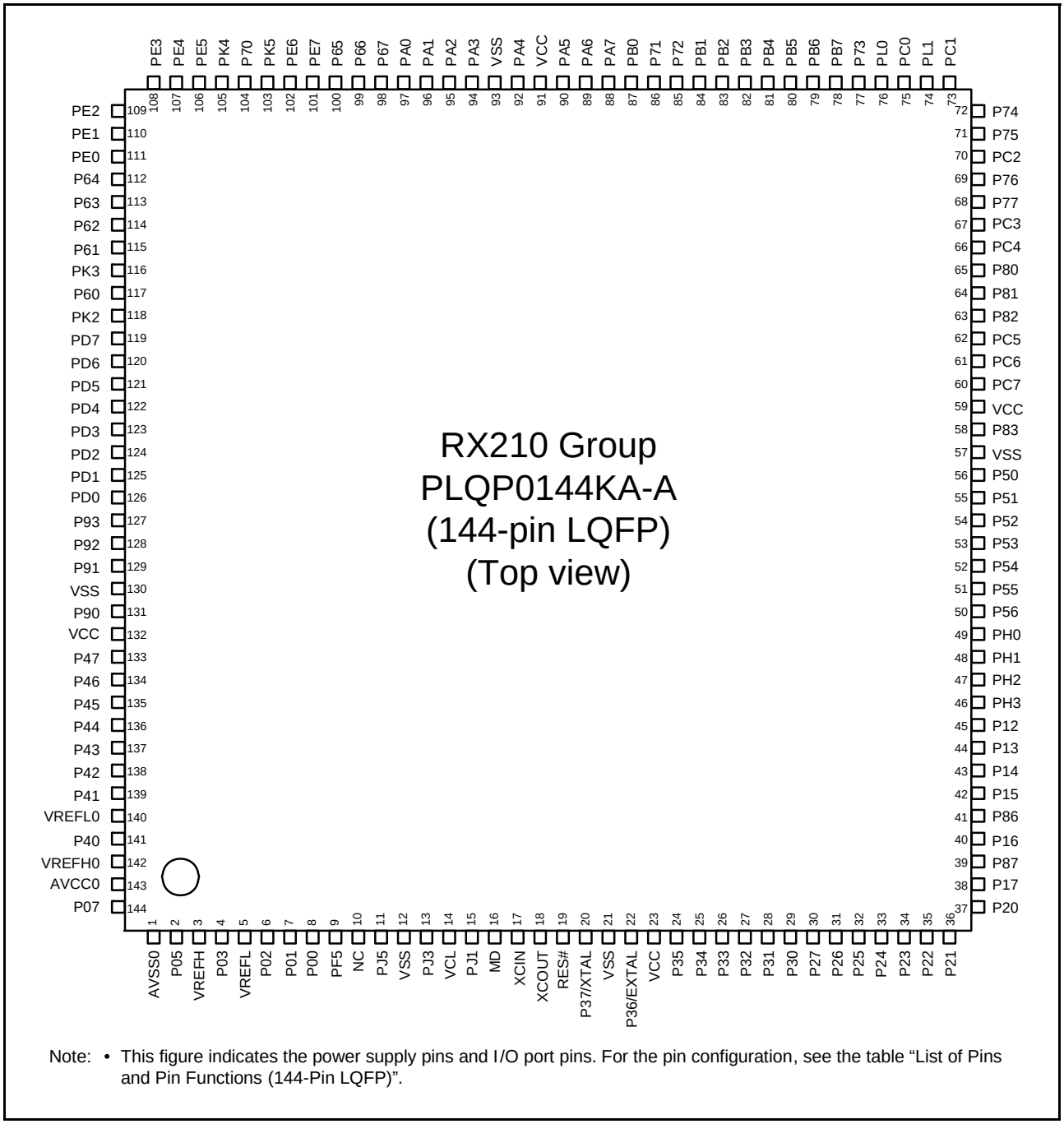
Applications of "Embedded - Microcontrollers"

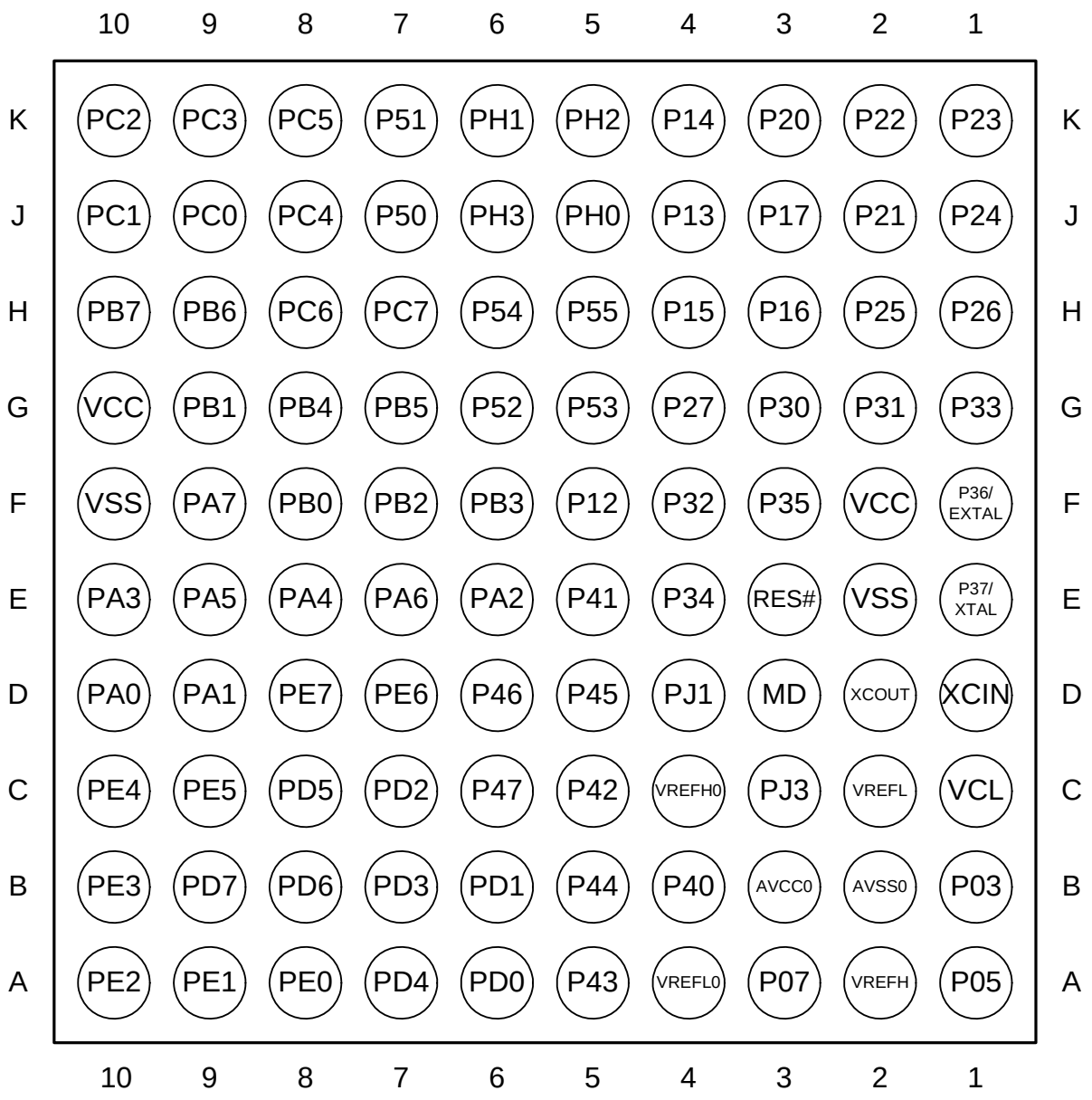
Details	
Product Status	Not For New Designs
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	EBI/EMI, I²C, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	122
Program Memory Size	768KB (768K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	96K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 5.5V
Data Converters	A/D 16x12b; D/A 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	145-TFLGA
Supplier Device Package	145-TFLGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f5210abdlk-u0



Note: • This figure indicates the power supply pins and I/O port pins. For the pin configuration, see the table “List of Pins and Pin Functions (144-Pin LQFP)”.

Figure 1.4 Pin Assignments of the 144-Pin LQFP

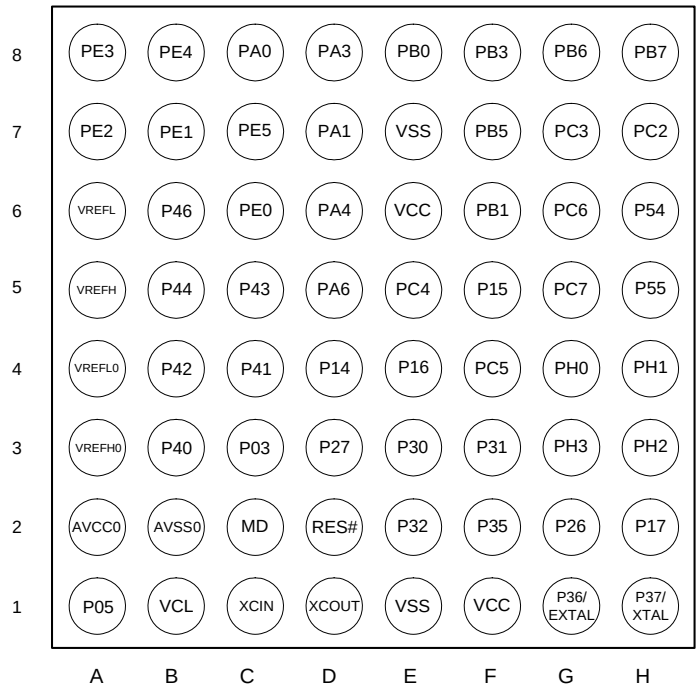
RX210 Group
PTLG0100JA-A
(100-pin TFLGA)
(Upper perspective view)



Note: • This figure indicates the power supply pins and I/O port pins. For the pin configuration, see the table “List of Pins and Pin Functions (100-Pin TFLGA)”.
Note: • For the position of A1 pin in the package, see “Package Dimensions”.

Figure 1.5 Pin Assignments of the 100-Pin TFLGA (Upper Perspective View)

RX210 Group
PTLG0064JA-A
(64-pin TFLGA)
(Upper perspective view)

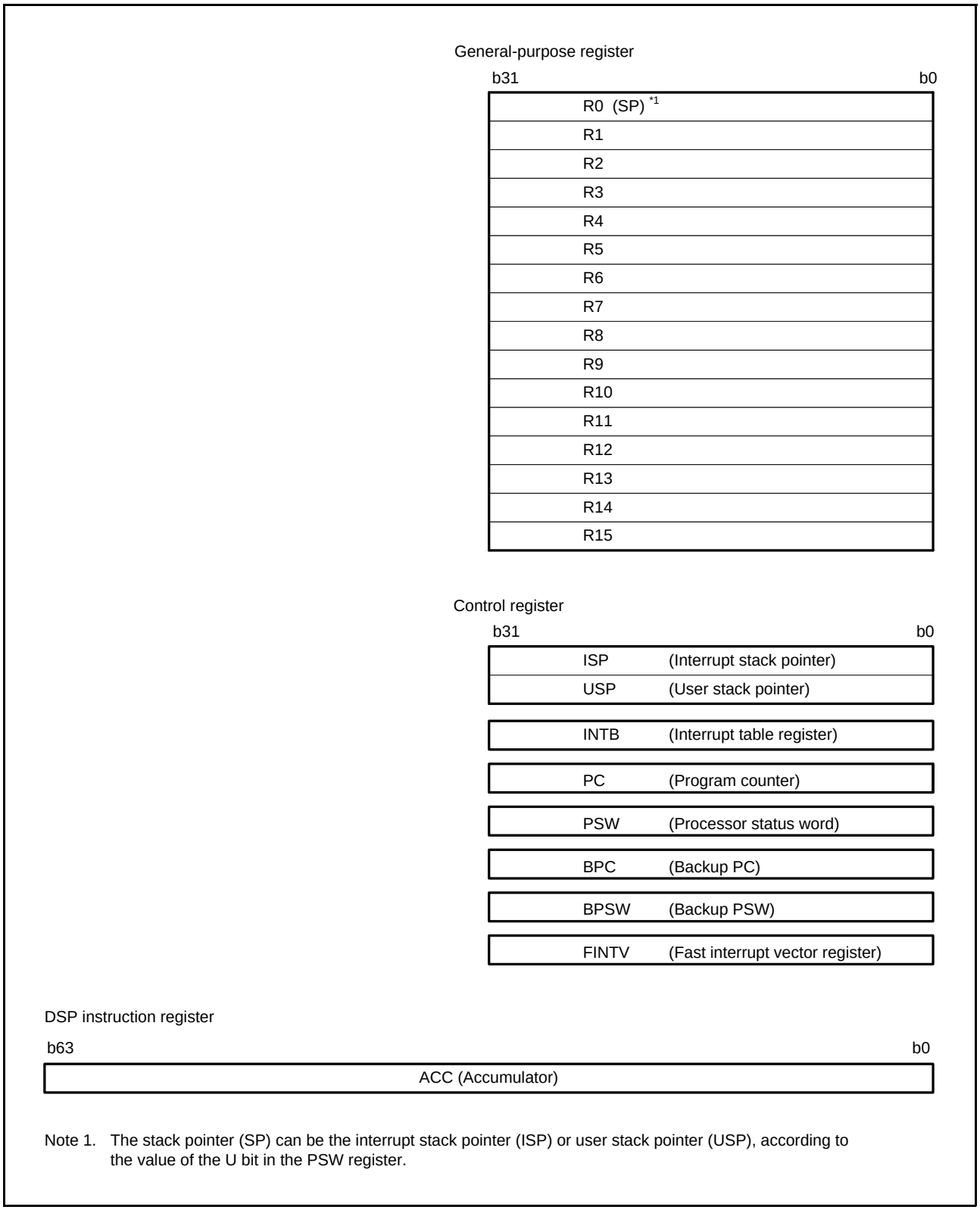


Note: • This figure indicates the power supply pins and I/O port pins. For the pin configuration, see the table “List of Pins and Pin Functions (64-Pin TFLGA)”.
Note: • For the position of A1 pin in the package, see “Package Dimensions”.

Figure 1.9 Pin Assignments of the 64-Pin TFLGA

2. CPU

Figure 2.1 shows the register set of the CPU.

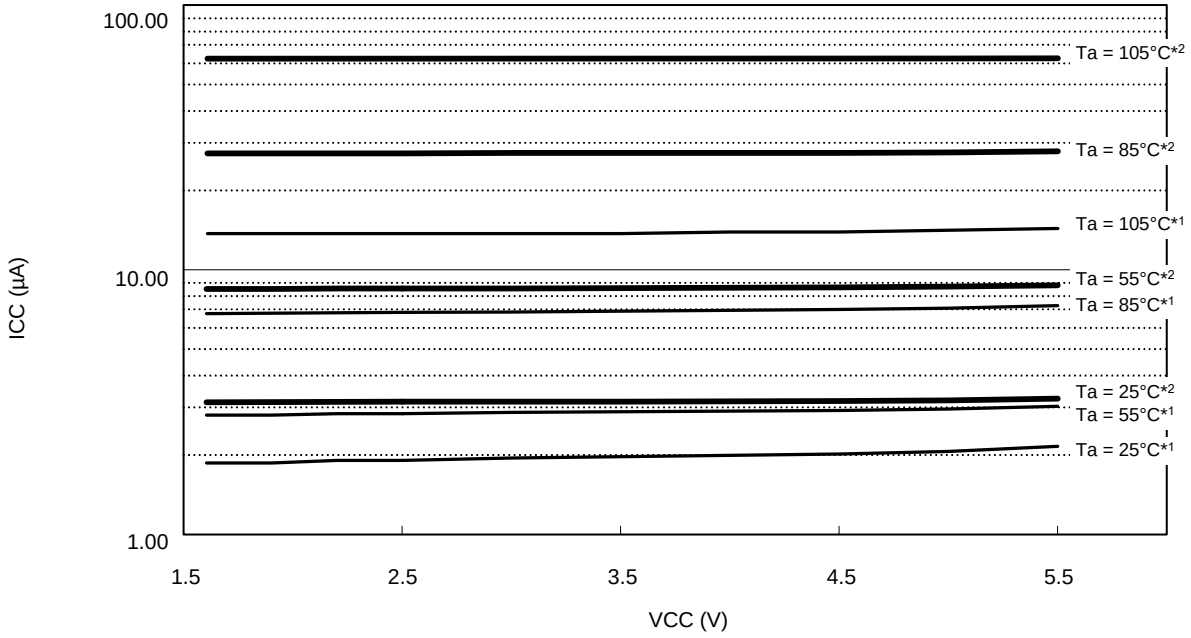


Note 1. The stack pointer (SP) can be the interrupt stack pointer (ISP) or user stack pointer (USP), according to the value of the U bit in the PSW register.

Figure 2.1 Register Set of the CPU

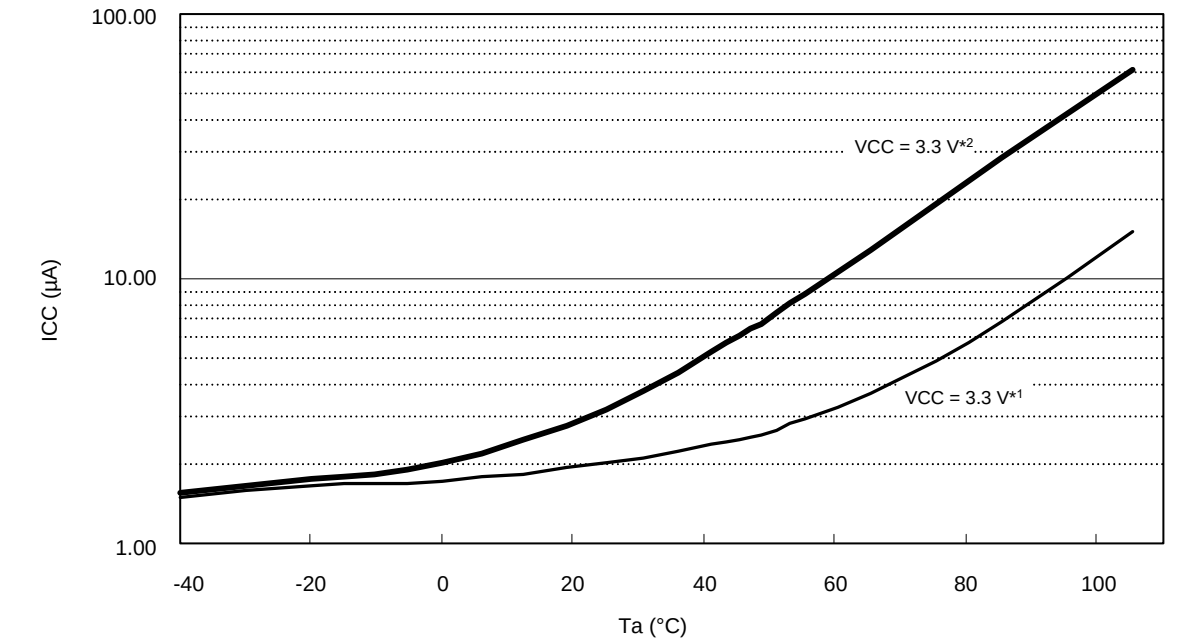
Table 4.1 List of I/O Registers (Address Order) (15 / 29)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles: ICLK ≥ PCLK	Number of Access Cycles: ICLK < PCLK
0008 8648h	MTU4	Timer A/D converter start request cycle set buffer register A	TADCOBRA	16	16	2, 3 PCLKB	2 ICLK
0008 864Ah	MTU4	Timer A/D converter start request cycle set buffer register B	TADCOBRB	16	16	2, 3 PCLKB	2 ICLK
0008 8660h	MTU	Timer waveform control register	TWCR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8680h	MTU	Timer start register	TSTR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8681h	MTU	Timer synchronous register	TSYR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8684h	MTU	Timer read/write enable register	TRWER	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8690h	MTU0	Noise filter control register	NFCR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8691h	MTU1	Noise filter control register	NFCR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8692h	MTU2	Noise filter control register	NFCR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8693h	MTU3	Noise filter control register	NFCR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8694h	MTU4	Noise filter control register	NFCR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8695h	MTU5	Noise filter control register	NFCR	8	8, 16	2, 3 PCLKB	2 ICLK
0008 8700h	MTU0	Timer control register	TCR	8	8	2, 3 PCLKB	2 ICLK
0008 8701h	MTU0	Timer mode register	TMDR	8	8	2, 3 PCLKB	2 ICLK
0008 8702h	MTU0	Timer I/O control register H	TIORH	8	8	2, 3 PCLKB	2 ICLK
0008 8703h	MTU0	Timer I/O control register L	TIORL	8	8	2, 3 PCLKB	2 ICLK
0008 8704h	MTU0	Timer interrupt enable register	TIER	8	8	2, 3 PCLKB	2 ICLK
0008 8705h	MTU0	Timer status register	TSR	8	8	2, 3 PCLKB	2 ICLK
0008 8706h	MTU0	Timer counter	TCNT	16	16	2, 3 PCLKB	2 ICLK
0008 8708h	MTU0	Timer general register A	TGRA	16	16	2, 3 PCLKB	2 ICLK
0008 870Ah	MTU0	Timer general register B	TGRB	16	16	2, 3 PCLKB	2 ICLK
0008 870Ch	MTU0	Timer general register C	TGRC	16	16	2, 3 PCLKB	2 ICLK
0008 870Eh	MTU0	Timer general register D	TGRD	16	16	2, 3 PCLKB	2 ICLK
0008 8720h	MTU0	Timer general register E	TGRE	16	16	2, 3 PCLKB	2 ICLK
0008 8722h	MTU0	Timer general register F	TGRF	16	16	2, 3 PCLKB	2 ICLK
0008 8724h	MTU0	Timer interrupt enable register 2	TIER2	8	8	2, 3 PCLKB	2 ICLK
0008 8726h	MTU0	Timer buffer operation transfer mode register	TBTM	8	8	2, 3 PCLKB	2 ICLK
0008 8780h	MTU1	Timer control register	TCR	8	8	2, 3 PCLKB	2 ICLK
0008 8781h	MTU1	Timer mode register	TMDR	8	8	2, 3 PCLKB	2 ICLK
0008 8782h	MTU1	Timer I/O control register	TIOR	8	8	2, 3 PCLKB	2 ICLK
0008 8784h	MTU1	Timer interrupt enable register	TIER	8	8	2, 3 PCLKB	2 ICLK
0008 8785h	MTU1	Timer status register	TSR	8	8	2, 3 PCLKB	2 ICLK
0008 8786h	MTU1	Timer counter	TCNT	16	16	2, 3 PCLKB	2 ICLK
0008 8788h	MTU1	Timer general register A	TGRA	16	16	2, 3 PCLKB	2 ICLK
0008 878Ah	MTU1	Timer general register B	TGRB	16	16	2, 3 PCLKB	2 ICLK
0008 8790h	MTU1	Timer input capture control register	TICCR	8	8	2, 3 PCLKB	2 ICLK
0008 8800h	MTU2	Timer control register	TCR	8	8	2, 3 PCLKB	2 ICLK
0008 8801h	MTU2	Timer mode register	TMDR	8	8	2, 3 PCLKB	2 ICLK
0008 8802h	MTU2	Timer I/O control register	TIOR	8	8	2, 3 PCLKB	2 ICLK
0008 8804h	MTU2	Timer interrupt enable register	TIER	8	8	2, 3 PCLKB	2 ICLK
0008 8805h	MTU2	Timer status register	TSR	8	8	2, 3 PCLKB	2 ICLK
0008 8806h	MTU2	Timer counter	TCNT	16	16	2, 3 PCLKB	2 ICLK
0008 8808h	MTU2	Timer general register A	TGRA	16	16	2, 3 PCLKB	2 ICLK
0008 880Ah	MTU2	Timer general register B	TGRB	16	16	2, 3 PCLKB	2 ICLK
0008 8880h	MTU5	Timer counter U	TCNTU	16	16	2, 3 PCLKB	2 ICLK
0008 8882h	MTU5	Timer general register U	TGRU	16	16	2, 3 PCLKB	2 ICLK
0008 8884h	MTU5	Timer control register U	TCRU	8	8	2, 3 PCLKB	2 ICLK
0008 8886h	MTU5	Timer I/O control register U	TIORU	8	8	2, 3 PCLKB	2 ICLK
0008 8890h	MTU5	Timer counter V	TCNTV	16	16	2, 3 PCLKB	2 ICLK
0008 8892h	MTU5	Timer general register V	TGRV	16	16	2, 3 PCLKB	2 ICLK
0008 8894h	MTU5	Timer control register V	TCRV	8	8	2, 3 PCLKB	2 ICLK



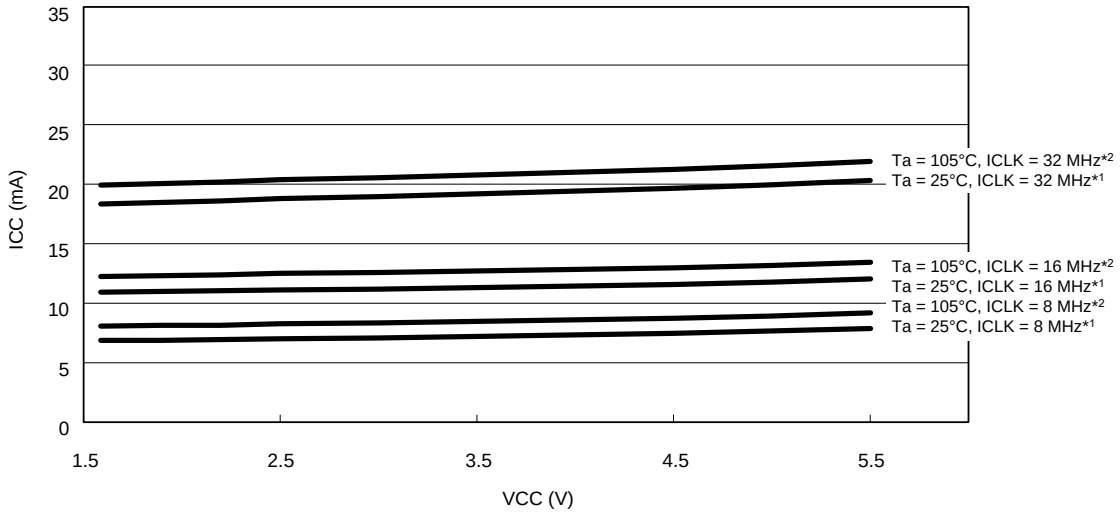
Note 1. Average value of the tested middle samples during product evaluation.
Note 2. Average value of the tested upper-limit samples during product evaluation.

Figure 5.5 Voltage Dependency in Software Standby Mode (SOFTCUT[2:0] Bits = 111b) (Reference Data) for Chip Version A



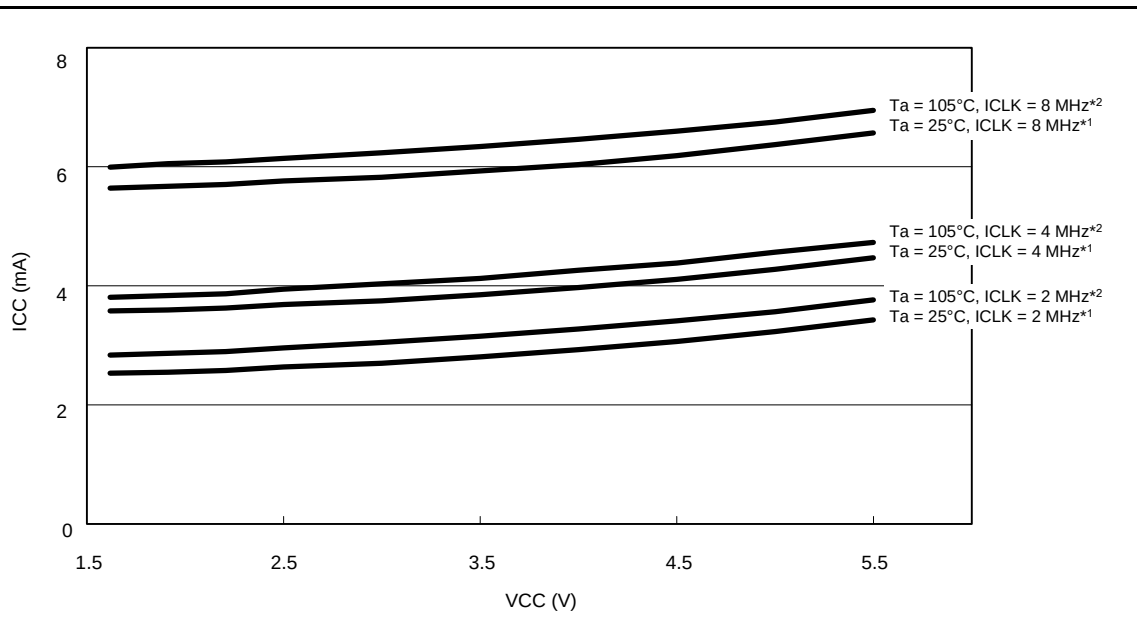
Note 1. Average value of the tested middle samples during product evaluation.
Note 2. Average value of the tested upper-limit samples during product evaluation.

Figure 5.6 Temperature Dependency in Software Standby Mode (SOFTCUT[2:0] Bits = 111b) (Reference Data) for Chip Version A



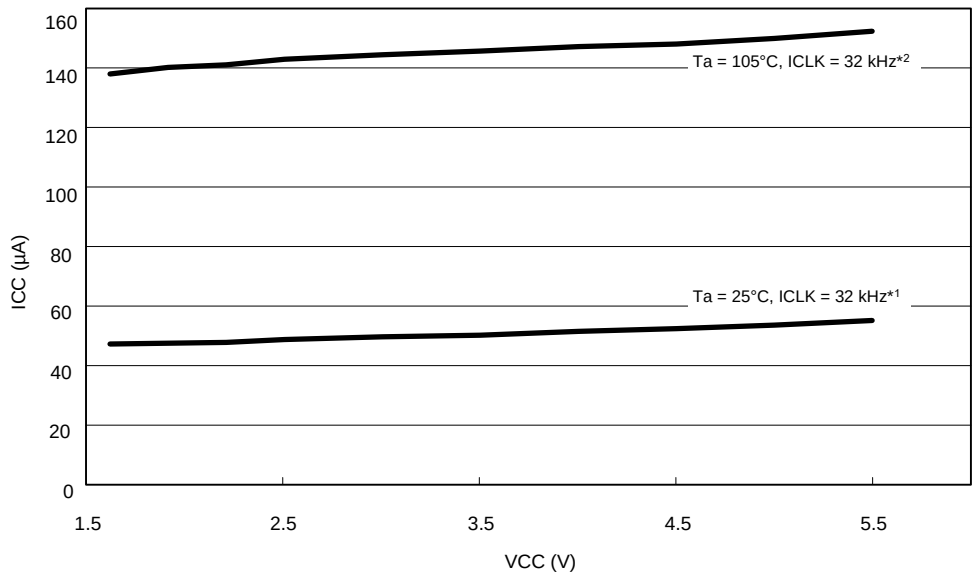
Note 1. All peripheral operation is normal. This does not include BGO operation.
Average value of the tested middle samples during product evaluation.
Note 2. All peripheral operation is maximum. This does not include BGO operation.
Average value of the tested upper-limit samples during product evaluation.

Figure 5.19 Voltage Dependency in Middle-Speed Operating Modes 2A and 2B (Reference Data) for Chip Version B with 256 Kbytes or Less of Flash Memory and 48 to 100 Pins



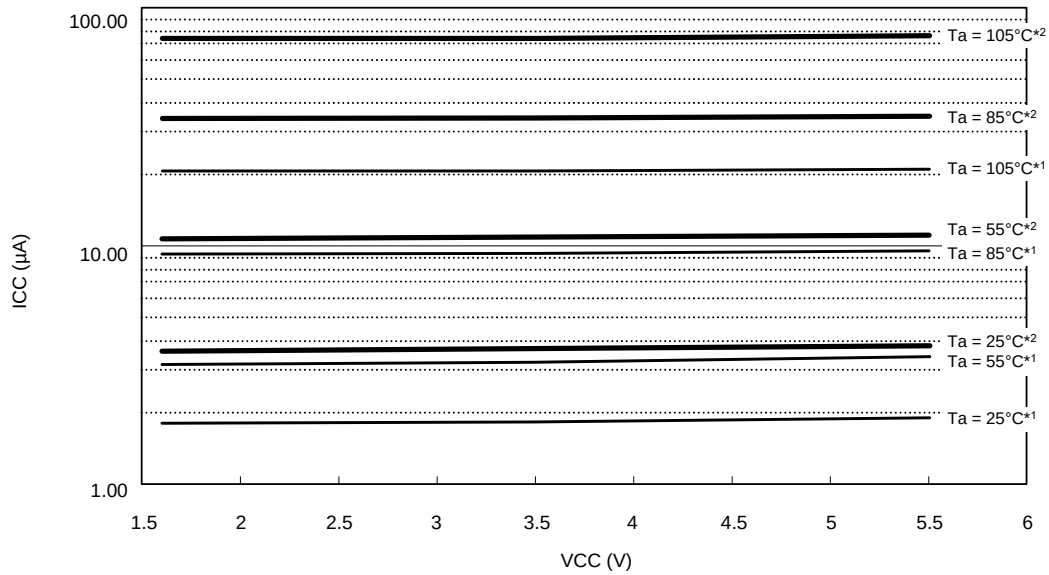
Note 1. All peripheral operation is normal.
Average value of the tested middle samples during product evaluation.
Note 2. All peripheral operation is maximum.
Average value of the tested upper-limit samples during product evaluation.

Figure 5.20 Voltage Dependency in Low-Speed Operating Mode 1 (Reference Data) for Chip Version B with 256 Kbytes or Less of Flash Memory and 48 to 100 Pins



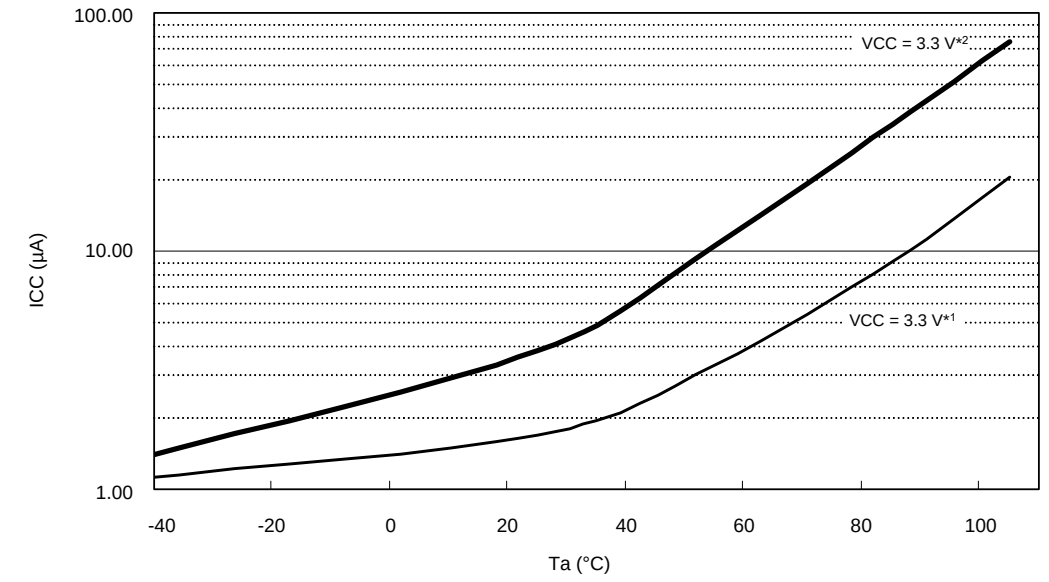
Note 1. All peripheral operation is normal.
Average value of the tested middle samples during product evaluation.
Note 2. All peripheral operation is maximum.
Average value of the tested upper-limit samples during product evaluation.

Figure 5.21 Voltage Dependency in Low-Speed Operating Mode 2 (Reference Data) for Chip Version B with 256 Kbytes or Less of Flash Memory and 48 to 100 Pins



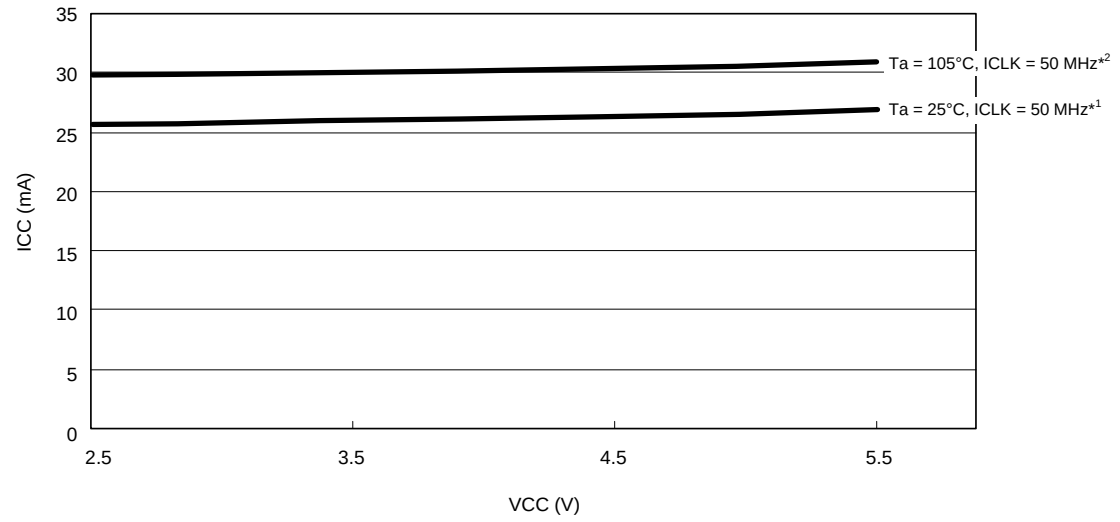
Note 1. Average value of the tested middle samples during product evaluation.
Note 2. Average value of the tested upper-limit samples during product evaluation.

Figure 5.22 Voltage Dependency in Software Standby Mode (SOFTCUT[2:0] Bits = 110b) (Reference Data) for Chip Version B with 256 Kbytes or Less of Flash Memory and 48 to 100 Pins



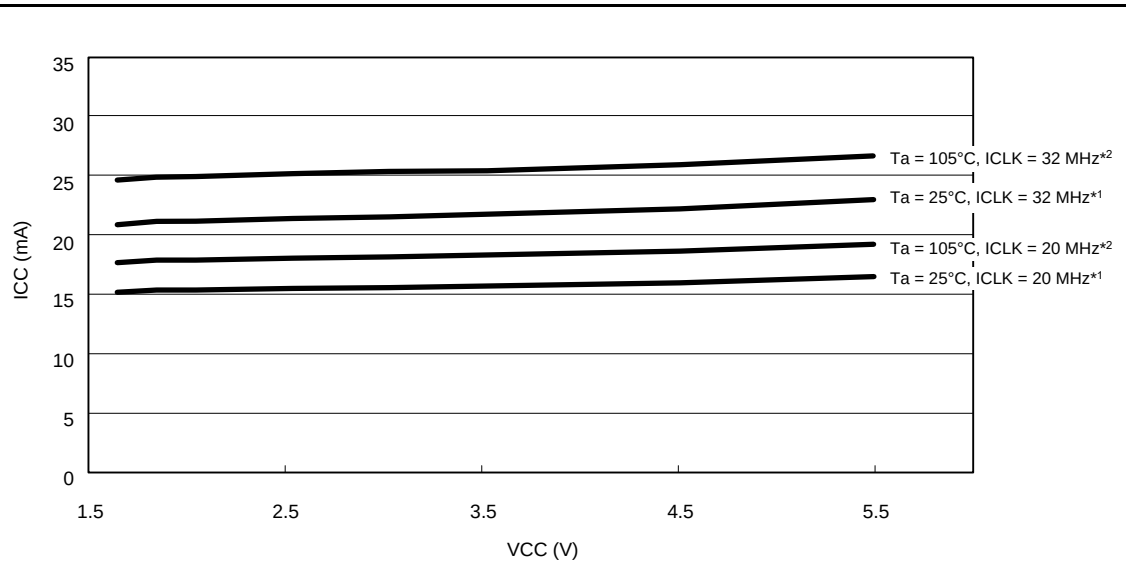
Note 1. Average value of the tested middle samples during product evaluation.
Note 2. Average value of the tested upper-limit samples during product evaluation.

Figure 5.23 Temperature Dependency in Software Standby Mode (SOFTCUT[2:0] Bits = 110b) (Reference Data) for Chip Version B with 256 Kbytes or Less of Flash Memory and 48 to 100 Pins



Note 1. All peripheral operation is normal. This does not include BGO operation.
Average value of the tested middle samples during product evaluation
Note 2. All peripheral operation is maximum. This does not include BGO operation.
Average value of the tested upper-limit samples during product evaluation.

Figure 5.35 Voltage Dependency in High-Speed Operating Mode (Reference Data) for Chip Version B with 512 Kbytes or Less of Flash Memory and 144 and 145 Pins



Note 1. All peripheral operation is normal. This does not include BGO operation.
Average value of the tested middle samples during product evaluation
Note 2. All peripheral operation is maximum. This does not include BGO operation.
Average value of the tested upper-limit samples during product evaluation.

Figure 5.36 Voltage Dependency in Middle-Speed Operating Modes 1A and 1B (Reference Data) for Chip Version B with 512 Kbytes or Less of Flash Memory and 144 and 145 Pins

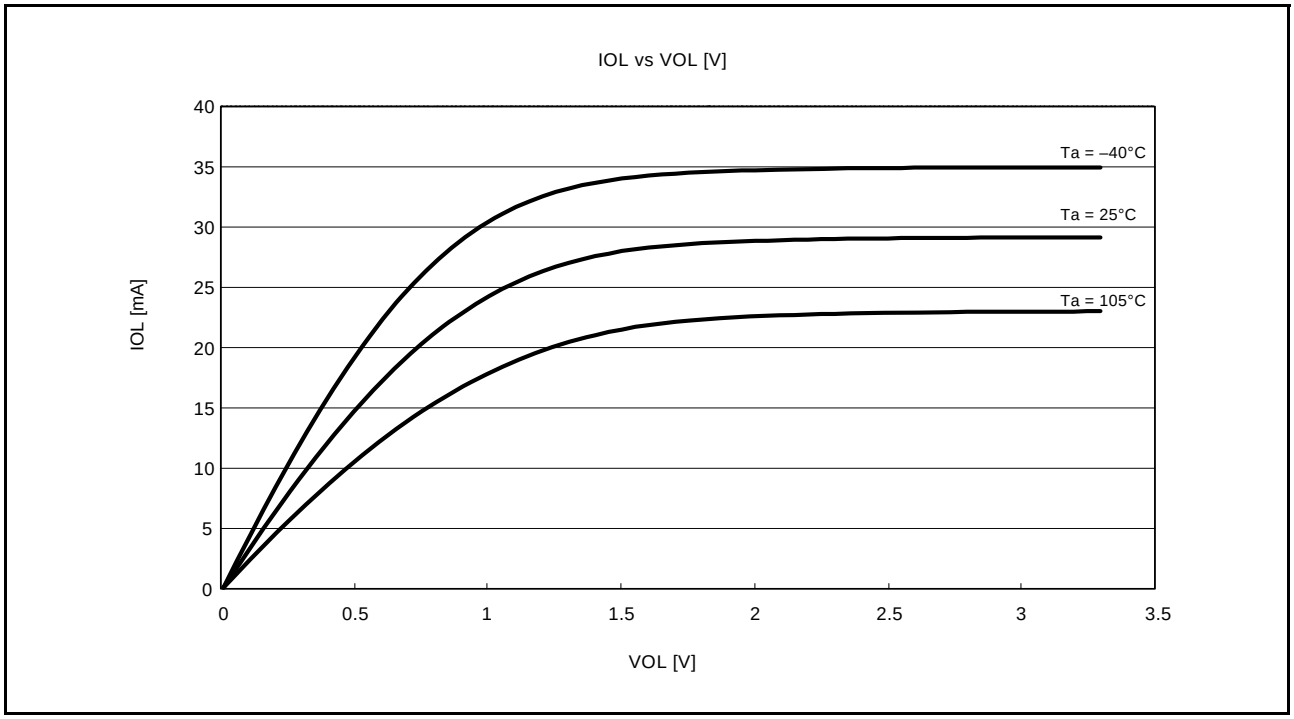


Figure 5.57 VOL and IOL Temperature Characteristics of RIIC Output Pin at VCC = 3.3 V (Reference Data)

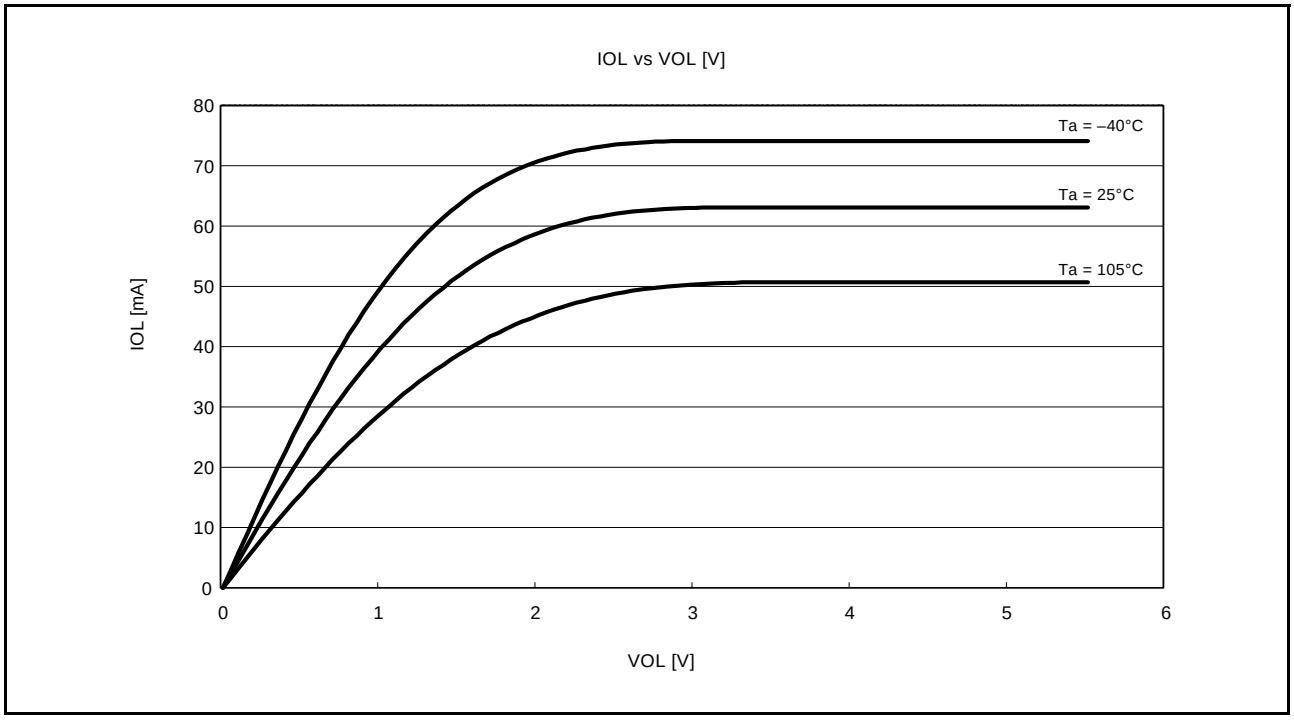


Figure 5.58 VOL and IOL Temperature Characteristics of RIIC Output Pin at VCC = 5.5 V (Reference Data)

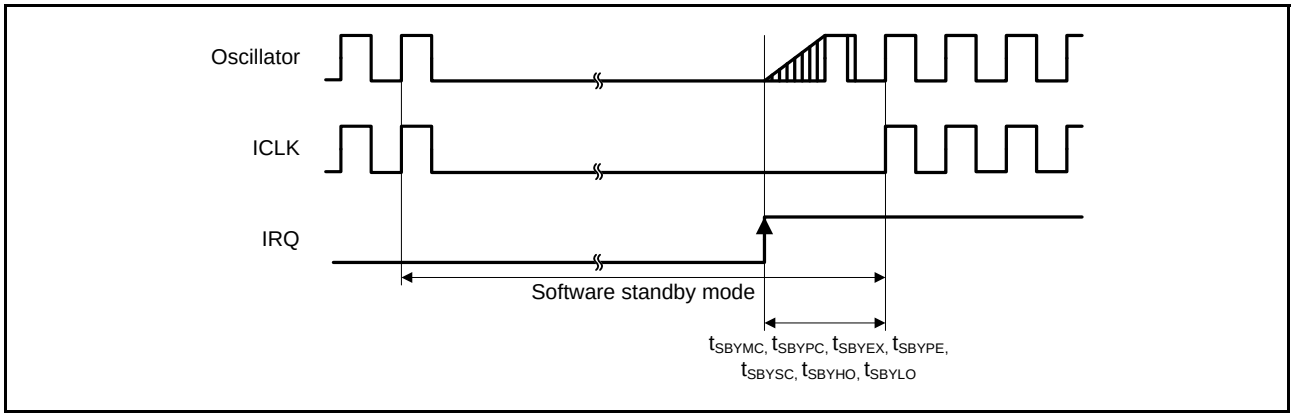


Figure 5.72 Software Standby Mode Cancellation Timing

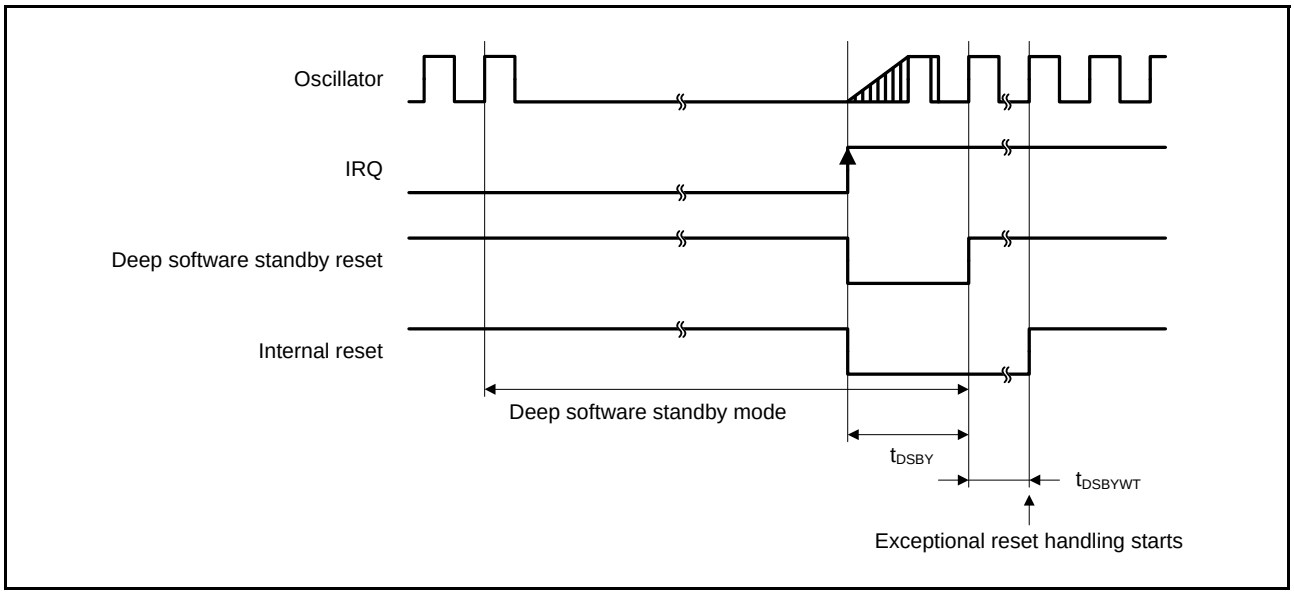


Figure 5.73 Deep Software Standby Mode Cancellation Timing

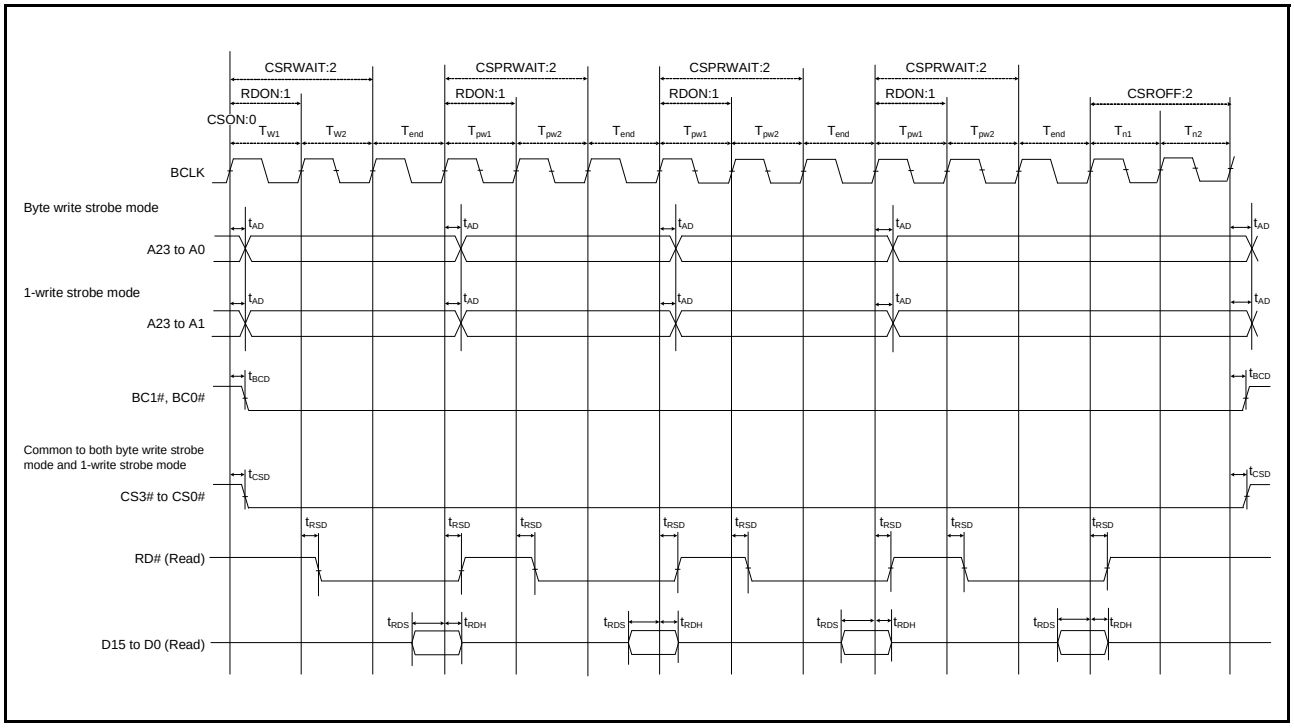
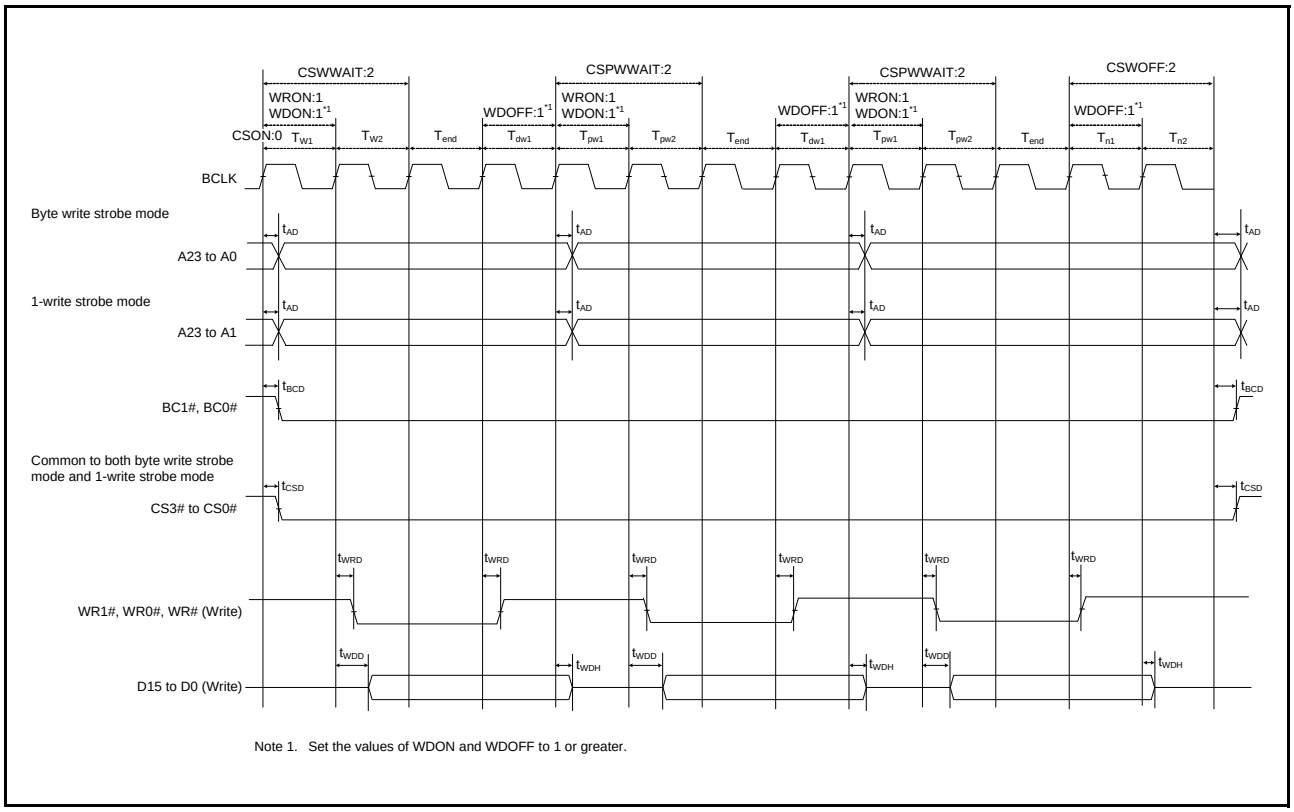


Figure 5.78 External Bus Timing/Page Read Cycle (Bus Clock Synchronized)



Note 1. Set the values of WDON and WDOFF to 1 or greater.

Figure 5.79 External Bus Timing/Page Write Cycle (Bus Clock Synchronized)

5.3.6 Timing of On-Chip Peripheral Modules

Table 5.55 Timing of On-Chip Peripheral Modules (1)

Conditions: VCC = AVCC0 = 1.62 to 5.5 V, VSS = AVSS0 = VREFL = VREFL0 = 0 V, T_a = –40 to +105°C
When high-drive output is selected by the drive capacity register

Item				Symbol	Min.	Max.	Unit	Test Conditions
I/O ports	Input data pulse width			t_{PRW}	1.5	—	t_{Pcyc}	Figure 5.83
MTU/ TPU	Input capture input pulse width		Single-edge setting	t_{TICW}	1.5	—	t_{Pcyc}	Figure 5.84
			Both-edge setting		2.5	—		
	Timer clock pulse width		Single-edge setting	t_{TCKWH}, t_{TCKWL}	1.5	—	t_{Pcyc}	Figure 5.85
			Both-edge setting		2.5	—		
			Phase counting mode		2.5	—		
POE	POE# input pulse width			t_{POEW}	1.5	—	t_{Pcyc}	Figure 5.86
8-bit timer	Timer clock pulse width		Single-edge setting	t_{TMCWH}, t_{TMCWL}	1.5	—	t_{Pcyc}	Figure 5.87
			Both-edge setting		2.5	—		
SCI	Input clock cycle		Asynchronous	t_{Scyc}	4	—	t_{Pcyc}	Figure 5.88
			Clock synchronous		6	—		
	Input clock pulse width			t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time			t_{SCKr}	—	20	ns	
	Input clock fall time			t_{SCKf}	—	20	ns	
	Output clock cycle		Asynchronous	t_{Scyc}	16	—	t_{Pcyc}	C = 30 pF Figure 5.89
			Clock synchronous		4	—		
	Output clock pulse width		2.7 V ≤ VCC ≤ 5.5 V	t_{SCKW}	0.4	0.6	t_{Scyc}	
			1.8 V ≤ VCC < 2.7 V		0.35	0.65		
			1.62 V ≤ VCC < 1.8 V		0.35	0.65		
	Output clock rise time			t_{SCKr}	—	20	ns	
	Output clock fall time			t_{SCKf}	—	20	ns	
	Transmit data delay time (master)	Clock synchronous		t_{TXD}	—	40	ns	
	Transmit data delay time (slave)	Clock synchronous	2.7 V ≤ VCC ≤ 5.5 V		—	65	ns	
			1.8 V ≤ VCC < 2.7 V		—	85	ns	
			1.62 V ≤ VCC < 1.8 V		—	95	ns	
	Receive data setup time (master)	Clock synchronous	2.7 V ≤ VCC ≤ 5.5 V	t_{RXS}	65	—	ns	
			1.8 V ≤ VCC < 2.7 V		75	—	ns	
			1.62 V ≤ VCC < 1.8 V		80	—	ns	
	Receive data setup time (slave)	Clock synchronous			40	—	ns	
	Receive data hold time	Clock synchronous		t_{RXH}	40	—	ns	
A/D converter	Trigger input pulse width			t_{TRGW}	1.5	—	t_{Pcyc}	Figure 5.90
CAC	CACREF input pulse width		$t_{Pcyc} \le t_{cac}$*2	t_{CACREF}	4.5 t_{cac} + 3 t_{Pcyc}	—	ns	
			$t_{Pcyc} > t_{cac}$*2		5 t_{cac} + 6.5 t_{Pcyc}			

Note 1. t_{Pcyc}: PCLK cycle
Note 2. t_{cac}: CAC count clock source cycle

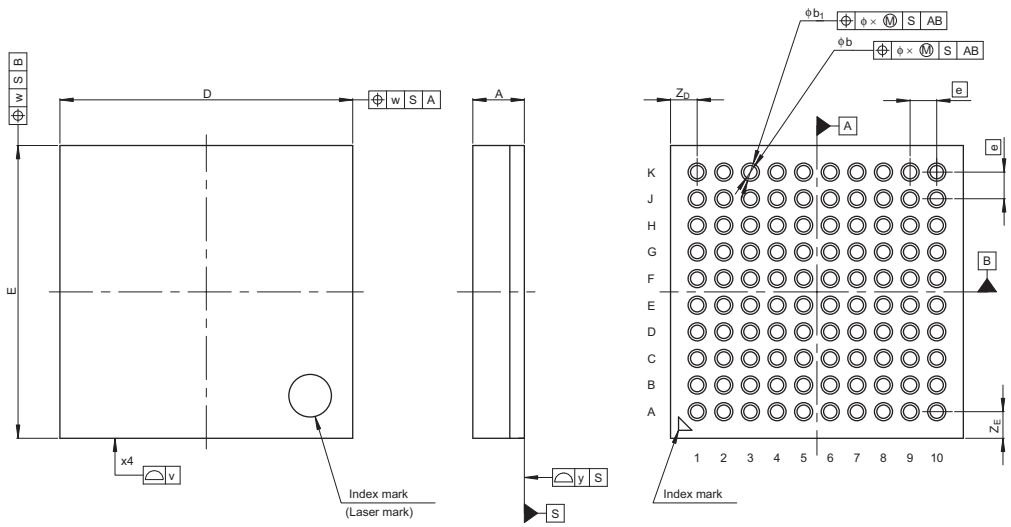
[Chip version B]

Table 5.78 ROM (Flash Memory for Code Storage) Characteristics (5) : middle-speed operating modes 1A and 2A

Conditions: VCC = AVCC0 = 2.7 to 5.5 V, VREFH = VREFH0 = AVCC0, VSS = AVSS0 = VREFL = VREFL0 = 0 V
Temperature range for the programming/erasure operation: T_a = –40 to +105°C

Item		Symbol	FCLK = 4 MHz			FCLK = 32 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time when N_{PEC} ≤ 100 times	2 bytes	t_{P2}	—	0.19	4.3	—	0.12	2.0	ms
	8 bytes	t_{P8}	—	0.19	4.4	—	0.12	2.0	
	128 bytes	t_{P128}	—	0.67	10.7	—	0.41	4.8	
Programming time when N_{PEC} > 100 times	2 bytes	t_{P2}	—	0.23	5.3	—	0.15	2.5	ms
	8 bytes	t_{P8}	—	0.23	5.4	—	0.15	2.5	
	128 bytes	t_{P128}	—	0.80	13.2	—	0.48	6.0	
Erasure time when N_{PEC} ≤ 100 times	2 Kbytes	t_{E2K}	—	13.0	92.9	—	10.5	29	ms
Erasure time when N_{PEC} > 100 times	2 Kbytes	t_{E2K}	—	15.9	176.9	—	12.8	60	ms
Suspend delay time during programming (in programming/erasure priority mode)		t_{SPD}	—	—	0.9	—	—	0.8	ms
First suspend delay time during programming (in suspend priority mode)		t_{SPSD1}	—	—	220	—	—	120	µs
Second suspend delay time during programming (in suspend priority mode)		t_{SPSD2}	—	—	0.9	—	—	0.8	ms
Suspend delay time during erasing (in programming/erasure priority mode)		t_{SED}	—	—	0.9	—	—	0.8	ms
First suspend delay time during erasing (in suspend priority mode)		t_{SESD1}	—	—	220	—	—	120	µs
Second suspend delay time during erasing (in suspend priority mode)		t_{SESD2}	—	—	0.9	—	—	0.8	ms
FCU reset time		t_{FCUR}	20 µs or longer and FCLK × 6 or greater	—	—	20 µs or longer and FCLK × 6 or greater	—	—	µs

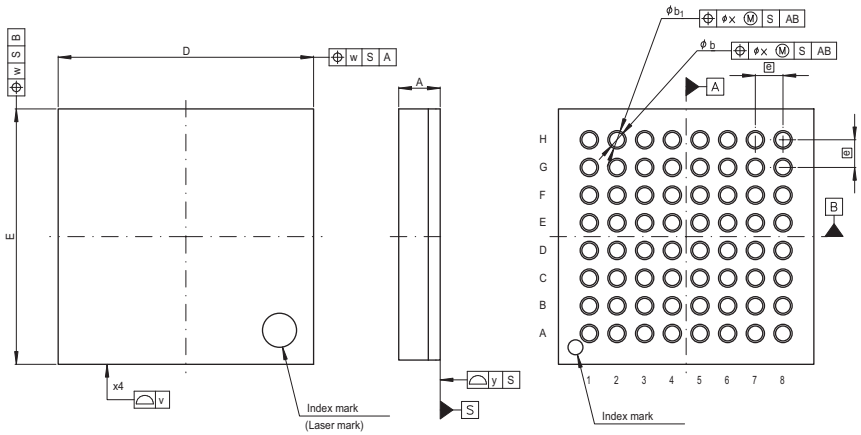
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TFLGA100-5.5x5.5-0.50	PTLG0100KA-A	100F0M	0.1g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	5.5	—
E	—	5.5	—
v	—	—	0.15
w	—	—	0.20
A	—	—	1.05
e	—	0.5	—
b	0.21	0.25	0.29
b_1	0.29	0.34	0.39
x	—	—	0.08
y	—	—	0.08
Z_D	—	0.5	—
Z_E	—	0.5	—

Figure D 100-Pin TFLGA (PTLG0100KA-A)

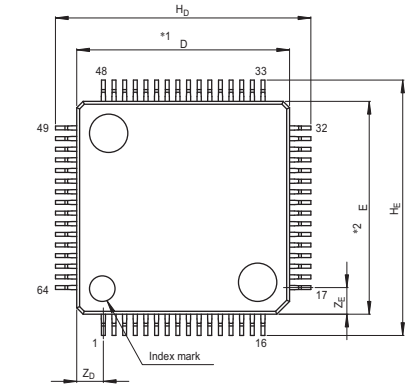
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TFLGA64-6x6-0.65	PTLG0064JA-A	64F0G	0.07g

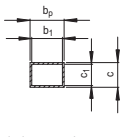


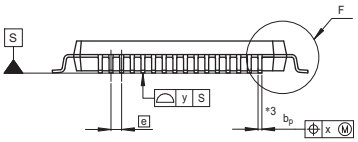
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	6.0	—
E	—	6.0	—
v	—	—	0.15
w	—	—	0.20
A	—	—	1.05
e	—	0.65	—
b	0.31	0.35	0.39
b_1	0.39	0.43	0.47
x	—	—	0.08
y	—	—	0.10

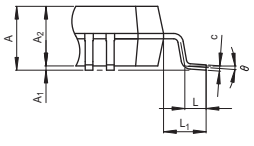
Figure F 64-Pin TFLGA (PTLG0064JA-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP64-10x10-0.50	PLQP0064KB-A	64P6Q-A / FP-64K / FP-64KV	0.3g







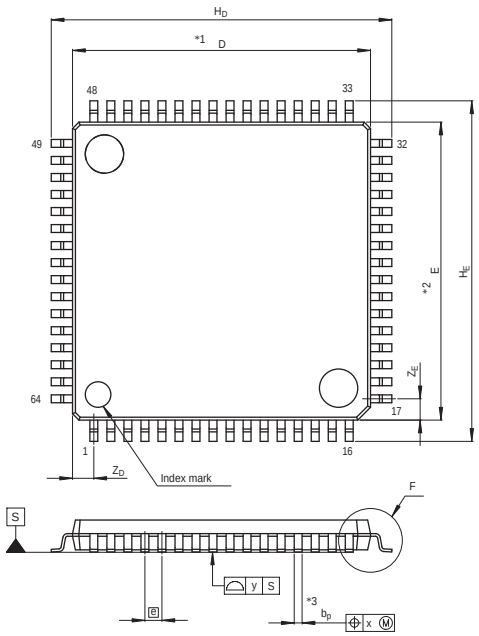


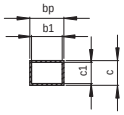
NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A_2	—	1.4	—
H_D	11.8	12.0	12.2
H_E	11.8	12.0	12.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.35	0.5	0.65
L_1	—	1.0	—

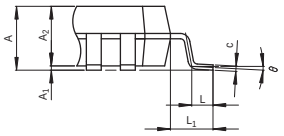
Figure J 64-Pin LQFP (PLQP0064KB-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/ —	0.7g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

Figure K 64-Pin LQFP (PLQP0064GA-A)

REVISION HISTORY	RX210 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.50	Apr.15, 2011	—	First edition, issued
0.90	Aug.10, 2011	1. Overview	
		4	Table 1.1 Outline of Specifications: Power supply voltage/ Operating frequency, changed
		17, 21, 24, 26	Table 1.5 to Table 1.8 List of Pins and Pin Functions (Pin name: LVCMP2 → CMPA2), changed
		2. CPU	
		51	Table 2.14 Instructions that are Converted into Multiple Micro-Operations (multiplier: 32 × 32 → 64 bits), (memory source operand), added
		4. I/O Registers	
		63	Table 5.1 List of I/O Registers (Address Order), SOSCWTCR, LOCOWTCR2, HOCOWTCR2, added
		114 to 116	Table 5.1 List of I/O Registers (Address Order): Interrupt source priority register, changed
		5. Electrical Characteristics	
		85 to 137	Newly added
1.20	Nov 28, 2012	All	Information on chip versions A, B, and C, corresponding descriptions and notes, added 48-pin products added, PLQP0080JA-A 14 × 14 mm, 0.65-mm pitch, package deleted
		Features	
		1	Description changed
		1. Overview	
		2	1.1 Outline of Specifications: Description, changed
		2 to 5	Table 1.1 Outline of Specifications, changed Note 1, added
		6	Table 1.2 Comparison of Functions for Different Packages, changed
		7	Table 1.3 List of Products, changed
		8 to 10	Tables 1.4 to 1.7 List of Products, added
		11	Figure 1.1 How to Read the Product Part No., Memory Capacity, and Package Type: G item added
		12	Figure 1.2 Block Diagram, changed
		13	Table 1.8 Pin Functions: Power supply and On-chip emulator, changed
		13	Table 1.8 Pin Functions: Multiplexed bus, added
		18	Figure 1.4 Pin Assignments of the 100-Pin LQFP, changed
		21	Figure 1.7 Pin Assignments of the 48-Pin LQFP, added
		23	Table 1.9 List of Pins and Pin Functions (100-Pin TFLGA): Pin No. G4, changed
		25	Table 1.10 List of Pins and Pin Functions (100-Pin LQFP): Pin No. 21, changed
		28	Table 1.11 List of Pins and Pin Functions (80-Pin LQFP): Pin No. 19, changed
		30	Table 1.12 List of Pins and Pin Functions (64-Pin LQFP): Pin No. 15, changed
		3. Address Space	
		37	Figure 3.1 Memory Map in Each Operating Mode: Note 2, changed
		4. I/O Registers	
		41 to 63	Table 4.1 List of I/O Registers (Address Order): Number of Access, changed Voltage regulator control register, Timeout internal counter L, Timeout internal counter U, and PLL power control register, added
		63	Table 4.1 List of I/O Registers (Address Order): Notes 1 and 2, added
		—	Table 4.1 List of I/O Registers (Address Order): LOCO Wait Control Register 2 (LOCOWTCR2), deleted
		5. Electrical Characteristics	
		64 to 152	Description added
1.30	Jan 22, 2013	Features	
		1	On-chip flash memory for code, no wait states, On-chip SRAM, no wait states, Real-time clock, Up to 15 communications channels, Up to 20 extended-function timers, changed
		1.Overview	
		2 to 6	Table 1.1 Outline of Specifications, changed
		7	Table 1.2 Comparison of Functions for Different Packages, changed
		9	Table 1.4 List of Products Chip Version B: D Version (Ta = -40 to +85°C), changed
		10	Table 1.5 List of Products Chip Version B: G Version (Ta = -40 to +105°C), changed